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Inventor Information for 10/723263

Inventor Name	City	State/Country
MATHIEU, GAETAN L.	LIVERMORE	CALIFORNIA
KHANDROS, IGOR Y.	ORINDA	CALIFORNIA
REYNOLDS, CARL	PLEASANTON	CALIFORNIA

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US 20020016902 A1	20020207	Computing system	712/11	712/16	Burtsev, Vsevolod Sergeevich et al.
US 20020011663 A1	20020131	FACE-UP SEMICONDUCTOR CHIP ASSEMBLIES	257/734	257/E21.511; 257/E21.606; 257/E21.705; 257/E23.004; 257/E23.019; 257/E23.061; 257/E23.065; 257/E23.066; 257/E23.067; 257/E23.07; 257/E23.124; 257/E23.13; 257/E25.029	Khandros, Igor Y. et al.
US 20020004320 A1	20020110	ATTARATUS FOR SOCKETABLY RECEIVING INTERCONNECTION ELEMENTS OF AN ELECTRONIC COMPONENT	439/66	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.004; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078;	PEDERSEN, DAVID V. et al.

				257/E23.172; 257/E23.181; 257/E25.011; 257/E25.029	
US 20010054905 A1	20011227	PROBE CARD ASSEMBLY AND KIT	324/754	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029	KHANDROS, IGOR Y. et al.
US 20010052786 A1	20011220	Special contact points for accessing internal circuitry of an integrated circuit	324/765	257/E23.079	Eldridge, Benjamin N. et al.
US 20010039109 A1	20011108	Lithographic contact elements	438/597	257/735; 257/773; 438/611; 438/666; 438/667	Mathieu, Gaetan L. et al.
US 20010038030 A1	20011108	Method and apparatus for shaping spring elements	228/155	228/180.5; 29/843; 361/776	Khandros, Igor Y. et al.
US 20010030370 A1	20011018	Microelectronic assembly having encapsulated wire bonding leads	257/778	257/691; 257/692; 257/723; 257/782; 257/E21.511; 257/E21.606; 257/E21.705; 257/E23.004; 257/E23.019; 257/E23.061; 257/E23.065; 257/E23.066; 257/E23.067; 257/E23.07; 257/E23.124; 257/E23.13; 257/E25.029	Khandros, Igor Y. et al.
US	20010913	Method of making and	430/311	430/318	Mathieu,

20010021483 A1		using lithographic contact springs			Gaetan L. et al.
US 20010020747 A1	20010913	Special contact points for accessing internal circuitry of an integrated circuit	257/779	257/738; 257/E23.079	Eldridge, Benjamin N. et al.
US 20010020743 A1	20010913	Special contact points for accessing internal circuitry of an integrated circuit	257/737	257/690; 257/692; 257/693; 257/738; 257/773; 257/E23.079	Eldridge, Benjamin N. et al.
US 20010020546 A1	20010913	Electrical contact structures formed by configuring a flexible wire to have a springable shape and overcoating the wire with at least one layer of a resilient conductive material, methods of mounting the contact structures to electronic components, and applications for employing the contact structures	174/261	174/24; 174/255; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029	Eldridge, Benjamin N. et al.
US 20010020545 A1	20010913	Electrical contact structures formed by configuring a flexible wire to have a springable shape and overcoating the wire with at least one layer of a resilient conductive material, methods of mounting the contact structures to electronic components, and applications for employing the contact structures	174/260	257/618; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 361/718; 361/736	Eldridge, Benjamin N. et al.
US 20010015773 A1	20010823	Special contact points for accessing internal circuitry of an	348/765	257/E23.079	Eldridge, Benjamin N. et al.

		integrated circuit			
US 20010015652 A1	20010823	Probe card assembly and kit, and methods of making same	324/761	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029	Eldridge, Benjamin Niles et al.
US 20010012739 A1	20010809	Composite microelectronic spring structure and method for making same	439/862	257/E23.021; 257/E23.068; 257/E23.078; 439/78	Grube, Gary W. et al.
US 20010002624 A1	20010607	TIP STRUCTURES.	174/250	174/260; 174/262; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029	KHANDROS, IGOR Y. et al.
US 20010002341 A1	20010531	Microelectronic contact structure, and method of making same	439/66		Eldridge, Benjamin N. et al.
US 20010002340 A1	20010531	Microelectronic contact structure, and method of making same.	439/66		Eldridge, Benjamin N. et al.
US 20010001570 A1	20010524	DECENTERED NONCORRECTIVE LENS FOR EYEWEAR	351/177	351/159; 351/41; 351/43; 351/44	HOUSTON, MALCOLM NEAL et al.
US 20010001080 A1	20010510	Interconnect assemblies and methods	438/611	257/735; 257/E21.582; 257/E23.014; 438/597	Eldridge, Benjamin N. et al.

US 7022382 B1	20060404	UV-cure of coatings for an optical fiber with a laser	427/513	118/620; 250/503.1; 250/504R; 427/163.1; 427/163.2; 427/444; 427/492; 427/508; 427/554; 65/392	Khudyakov; Igor Vladimir et al.
US 7021488 B2	20060404	Pressure vessel for compressed gases utilizing a replaceable and flexible liner	220/586	220/495.06; 220/581; 220/723	Thompson; Scott R.
US 7011299 B2	20060314	Liquid vapor delivery system and method of maintaining a constant level of fluid therein	261/66	261/121.1; 261/127; 261/DIG.65	Curran; William J.
US 7010854 B2	20060314	Re-assembly process for MEMS structures	29/832	29/842; 29/844; 324/754; 324/762; 438/462; 438/464	Eldridge; Benjamin N. et al.
US D516130 S	20060228	Head member for a chess piece	D21/388		Mathe; Gary W.
US 7005751 B2	20060228	Layered microelectronic contact and method for fabricating same	257/780	257/773; 29/842	Khandros; Igor Y. et al.
US 7004582 B2	20060228	Electronically enabled eyewear	351/158	381/150	Jannard; James et al.
US 7002363 B2	20060221	Method and system for compensating thermally induced motion of probe cards	324/758	324/324; 324/754; 324/762	Mathieu; Gaetan L.
US 6982752 B2	20060103	Circuit and method for correcting a digital color sampled signal	348/222.1	348/241; 382/167	Kharitoneko; Igor et al.
US 6972578 B2	20051206	Method and system for compensating thermally induced motion of probe cards	324/754	324/158.1	Martens; Rod et al.
US 6960923 B2	20051101	Probe card covering system and method	324/754	439/135; 439/136	Eldridge; Benjamin N. et al.

US 6956174 B2	20051018	Tip structures	174/267	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029	Khandros; Igor Y. et al.
US 6945827 B2	20050920	Microelectronic contact structure	439/700	361/761	Grube; Gary W. et al.
US 6943202 B2	20050913	Radiation-curable polyurethane	522/90	522/97; 526/301	Zhu; Zhenya et al.
US 6940093 B2	20050906	Special contact points for accessing internal circuitry of an integrated circuit	257/48	257/690; 257/779; 257/786; 257/E23.079	Eldridge; Benjamin N. et al.
US 6937037 B2	20050830	Probe card assembly for contacting a device with raised contact elements	324/754	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 324/761	Eldridge; Benjamin N. et al.
US 6932869 B2	20050823	UV-cure of coating for optical fiber assisted by ultrasound	118/125	118/642; 118/67	Overton; Bob J. et al.
US 6920689 B2	20050726	Method for making a socket to perform testing on integrated circuits	29/860	29/825; 29/840; 29/843; 29/870; 29/874; 29/877; 29/878; 29/885; 324/356;	Khandros; Igor Y. et al.

				439/54	
US 6913468 B2	20050705	Methods of removably mounting electronic components to a circuit board, and sockets formed by the methods	439/66	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.025; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 439/83	Dozier, II; Thomas H. et al.
US 6911065 B2	20050628	Method and system for supplying high purity fluid	95/90	55/385.4; 95/115; 95/116; 95/131; 95/133; 95/135; 95/138; 95/139; 95/140; 95/143; 96/112; 96/135; 96/138; 96/143; 96/151; 96/153	Watanabe; Tadaharu et al.
US 6900252 B2	20050531	UV-curable acrylate coatings for food packaging	522/182	427/487; 427/496; 427/508; 522/113; 522/120; 522/121; 522/178; 522/180; 53/461	Khudyakov; Igor Vladimir et al.
US 6888229 B2	20050503	Connection components with frangible leads and bus	257/666	257/667; 257/668; 257/669; 257/670; 257/671;	DiStefano; Thomas H. et al.

				257/674; 257/676; 257/E21.516; 257/E23.055; 257/E23.124	
US 6887918 B2	20050503	Formulation of UV-curable coatings for optical fiber for a fast cure	522/96	385/147; 427/508; 427/512; 427/513; 428/378; 522/120; 522/121; 522/150; 522/151; 522/152; 522/181; 522/182; 522/40; 522/41; 522/42; 522/43; 522/44; 522/45; 522/46; 522/47; 522/48; 522/49; 522/77; 522/90	Khudyakov; Igor V. et al.
US 6885165 B2	20050426	Patient bed for multiple position emission scans	318/687	318/135; 5/611; 5/621	Henley; Alan W. et al.
US 6864105 B2	20050308	Method of manufacturing a probe card	438/14	716/4	Grube; Gary W. et al.
US 6859600 B2	20050222	Coated optical fiber and optical fiber ribbon and method for the fabrication thereof	385/128	385/114; 427/163.1; 427/163.2; 65/385; 65/430; 65/443; 65/529	Khudyakov; Igor V. et al.
US 6842235 B2	20050111	Optical measurement of planarized features	356/72	356/237.2	Zaidi; Syed Shoaib Hasan et al.
US 6840374 B2	20050111	Apparatus and method for cleaning test probes	206/223	428/145; 428/447;	Khandros; Igor Y. et al.

				428/450; 428/688	
US 6838893 B2	20050104	Probe card assembly	324/754	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.025; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 324/761	Khandros, Jr.; Igor Y. et al.
US 6838444 B1	20050104	Compositions and methods for the therapeutic use of an atonal-associated sequence for deafness, osteoarthritis, and abnormal cell proliferation	514/44	435/320.1; 536/23.1	Zoghbi; Huda Y. et al.
US 6836962 B2	20050104	Method and apparatus for shaping spring elements	29/844	29/842; 29/843; 29/876; 29/878; 29/879	Khandros; Igor Y. et al.
US 6835898 B2	20041228	ELECTRICAL CONTACT STRUCTURES FORMED BY CONFIGURING A FLEXIBLE WIRE TO HAVE A SPRINGABLE SHAPE AND OVERCOATING THE WIRE WITH AT LEAST ONE LAYER OF A RESILIENT CONDUCTIVE MATERIAL, METHODS OF MOUNTING THE	174/267	174/260; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029	Eldridge; Benjamin N. et al.

		CONTACT STRUCTURES TO ELECTRONIC COMPONENTS, AND APPLICATIONS FOR EMPLOYING THE CONTACT STRUCTURES			
US 6827584 B2	20041207	Interconnect for microelectronic structures with enhanced spring characteristics	439/66	257/E23.021; 257/E23.078; 438/117	Mathieu; Gaetan L. et al.
US 6825422 B2	20041130	Interconnection element with contact blade	174/260	174/267; 361/772; 361/776; 439/81	Eldridge; Benjamin N. et al.
US 6825052 B2	20041130	Test assembly including a test die for testing a semiconductor product die	438/15	257/E23.021; 257/E23.068; 257/E23.078; 324/527; 324/528; 324/754; 324/755; 324/763; 324/765; 438/14; 438/18	Eldridge; Benjamin N. et al.
US 6824589 B2	20041130	Materials and methods for the purification of inert, nonreactive, and reactive gases	95/117	95/137; 95/138; 95/139; 95/140	Watanabe; Tadaharu et al.
US 6821900 B2	20041123	Method for dry etching deep trenches in a substrate	438/700	438/710; 438/713; 438/714; 438/719	Athavale; Satish et al.
US 6821864 B2	20041123	Method to achieve increased trench depth, independent of CD as defined by lithography	438/429	257/E21.232; 257/E21.546; 257/E21.59; 438/269	Chan; Kevin K. et al.
US 6820353 B2	20041123	Performance shoe midsole	36/29	36/28	Oman; James D. et al.
US 6818840 B2	20041116	Method for manufacturing raised electrical contact pattern of controlled	174/267	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511;	Khandros; Igor Y.

		geometry		257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.025; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 361/776	
US 6809005 B2	20041026	Method to fill deep trench structures with void-free polysilicon or silicon	438/426	257/E21.572; 438/388; 438/422	Ranade; Rajiv et al.
US 6807734 B2	20041026	Microelectronic contact structures, and methods of making same	29/874	29/842; 29/882; 29/889; 438/106	Eldridge; Benjamin N. et al.
US 6797036 B2	20040928	Method for removing impurities from process gas stream	95/90	95/141	Funke; Hans H. et al.
US 6791176 B2	20040914	Lithographic contact elements	257/690	257/620; 257/691; 257/692; 257/693; 438/14; 438/15; 438/50; 438/52	Mathieu; Gaetan L. et al.
US 6790358 B2	20040914	Composition for removing trace impurities from inert, non-reactive and reactive liquids	210/502.1	210/906; 210/909; 210/915	Funke; Hans H. et al.
US 6788094 B2	20040907	Wafer-level burn-in and test	324/765		Khandros; Igor Y. et al.
US 6783577 B2	20040831	Gas purifier system containing an ultra-low emission carbon material	96/108	502/416; 502/519; 96/121; 96/132; 96/133	Funke; Hans H. et al.
US 6783576 B2	20040831	Gas purifier system for removing trace impurities from a reactive fluid	96/108	206/.7; 502/519; 96/121; 96/132; 96/133;	Funke; Hans H. et al.

				96/153	
US 6778406 B2	20040817	Resilient contact structures for interconnecting electronic devices	361/776	174/260; 257/784; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 361/773; 361/774	Eldridge; Benjamin N. et al.
US 6777319 B2	20040817	Microelectronic spring contact repair	438/612	257/E21.508; 257/E23.025; 438/4; 438/52; 438/669; 438/678	Grube; Gary W. et al.
US 6762600 B2	20040713	Method and apparatus for electromagnetic position and orientation tracking with distortion compensation employing a modulated signal	324/207.17	324/247; 324/248; 324/252; 324/253; 600/407; 600/424; 702/150	Khalfin; Igor
US 6759311 B2	20040706	Fan out of interconnect elements attached to semiconductor wafer	438/460	257/E21.508; 257/E23.014; 257/E23.025; 438/113; 438/117; 438/461; 438/462; 438/617	Eldridge; Benjamin N. et al.
US 6743727 B2	20040601	Method of etching high aspect ratio openings	438/695	216/37; 216/46; 216/67; 216/79; 438/702; 438/703; 438/714	Mathad; Gangadhara S. et al.

US 6741085 B1	20040525	Contact carriers (tiles) for populating larger substrates with spring contacts	324/754	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.025; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029	Khandros; Igor Y. et al.
US 6733734 B2	20040511	Materials and methods for the purification of hydride gases	423/219	423/210; 423/347; 423/352; 502/304; 502/326; 502/345; 502/349; 502/353; 502/406; 95/117; 95/138; 96/154	Watanabe; Tadaharu et al.
US 6729019 B2	20040504	Method of manufacturing a probe card	29/830	29/592.1; 29/593; 29/825; 29/832; 29/892	Grube; Gary W. et al.
US 6727580 B1	20040427	Microelectronic spring contact elements	257/692	228/179.1; 257/773; 438/117	Eldridge; Benjamin N. et al.
US 6727579 B1	20040427	ELECTRICAL CONTACT STRUCTURES FORMED BY CONFIGURING A FLEXIBLE WIRE TO HAVE A SPRINGABLE SHAPE AND OVERCOATING THE WIRE WITH AT LEAST ONE LAYER OF A RESILIENT	257/692	257/697; 257/784; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068;	Eldridge; Benjamin N. et al.

		CONDUCTIVE MATERIAL, METHODS OF MOUNTING THE CONTACT STRUCTURES TO ELECTRONIC COMPONENTS, AND APPLICATIONS FOR EMPLOYING THE CONTACT STRUCTURES		257/E23.078; 257/E25.011; 257/E25.029	
US 6720282 B2	20040413	Method for producing a preconditioned ultra-low emission carbon material	502/180	502/416	Funke; Hans H. et al.
US 6719204 B2	20040413	Mathieu-Gaussian beam for optical scanners	235/462.22	235/454; 235/462.01; 235/462.32	Li; Yajun
US 6713374 B2	20040330	Interconnect assemblies and methods	438/611	257/735; 257/E21.582; 257/E23.014; 438/117	Eldridge; Benjamin N. et al.
US 6710012 B2	20040323	Method for producing an ultra-low emission carbon material	502/416	502/439; 502/519; 53/432; 73/29.01	Funke; Hans H. et al.
US 6709917 B2	20040323	Method to increase the etch rate and depth in high aspect ratio structure	438/243	257/E21.218; 438/386; 438/735	Panda; Siddhartha et al.
US 6709482 B2	20040323	Method for reducing trace impurities from a reactive fluid using preconditioned ultra-low emission carbon material	95/8	502/418; 95/117; 95/139; 95/140; 95/143; 95/901	Funke; Hans H. et al.
US 6701612 B2	20040309	Method and apparatus for shaping spring elements	29/842	29/843; 29/874; 324/756; 439/591; 439/66	Khandros; Igor Y. et al.
US 6690185 B1	20040210	Large contactor with multiple, aligned contactor units	324/758	228/180.22; 361/760	Khandros; Igor Y et al.
US 6687014	20040203	Method for monitoring	356/504		Zaidi; Shoaib

B2		the rate of etching of a semiconductor			Hasan et al.
US 6685817 B1	20040203	Method and apparatus for controlling plating over a face of a substrate	205/137	118/52; 204/212; 204/224R; 204/241; 204/275.1; 205/148; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 427/425; 427/430.1	Mathieu; Gaetan L.
US 6672875 B1	20040106	Spring interconnect structures	439/66	439/515; 439/83; 439/862	Mathieu; Gaetan L. et al.
US 6669489 B1	20031230	Interposer, socket and assembly for socketing an electronic component and method of making and using same	439/71	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.025; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 439/66; 439/83; 439/886	Dozier, II; Thomas H. et al.
US 6664628 B2	20031216	Electronic component overlapping dice of unsingulated	257/723	257/724; 257/E23.079; 257/E25.011;	Khandros; Igor Y. et al.

		semiconductor wafer		361/782; 361/783; 438/107; 438/110; 438/113; 438/462	
US 6655023 B1	20031202	Method and apparatus for burning-in semiconductor devices in wafer form	29/843	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.025; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 29/825; 29/842; 29/874; 29/883	Eldridge; Benjamin N. et al.
US 6642625 B2	20031104	Sockets for "springed" semiconductor devices	257/774	257/698; 257/781; 257/784; 257/E23.004; 257/E23.078; 257/E23.172; 257/E23.181; 439/438; 439/448	Dozier, II; Thomas H. et al.
US 6640432 B1	20031104	Method of fabricating shaped springs	29/842	257/E23.021; 257/E23.078; 29/843; 29/874; 29/884; 439/66; 439/79; 439/886	Mathieu; Gaetan L. et al.
US 6637212 B2	20031028	Method and apparatus for the delivery of liquefied gases having constant impurity levels	62/50.2		Torres, Jr.; Robert et al.
US 6624648	20030923	Probe card assembly	324/761	257/E21.503;	Eldridge;

B2				257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 324/754	Benjamin N. et al.
US 6624626 B2	20030923	Method and apparatus for electromagnetic position and orientation tracking with distortion compensation employing modulated signal	324/207.17	324/207.12; 702/150	Khalfin; Igor
US 6621970 B2	20030916	UV-curable optical fiber coating composition including fullerenes	385/128	385/123; 385/127; 427/163.2; 977/734; 977/788; 977/890; 977/892 CIPG 20060101 A C03C C03C25/10 L I R US M 20060101 CICL C03C CIPS C03C25/10 20060101 CIPG 20060101 A C03C C03C25/10 L I R US M 20060101 CICL C03C CIPS C03C25/10	Khudyakov; Igor V. et al.

				20060101 CIPG 20060101 A C03C C03C25/24 L I R US M 20060101 CICL C03C CIPS C03C25/24; 20060101 CIPG 20060101 A C03C C03C25/28 L I R US M 20060101 CICL C03C CIPS C03C25/28 20060101	
US 6621260 B2	20030916	Special contact points for accessing internal circuitry of an integrated circuit	324/158.1	257/E23.079; 361/111; 361/56; 361/58	Eldridge; Benjamin N. et al.
US 6616966 B2	20030909	Method of making lithographic contact springs	29/842	205/125; 427/272; 427/282; 427/307; 427/96.8; 427/97.4; 430/312; 430/314; 430/315; 430/316	Mathieu; Gaetan L. et al.
US 6615485 B2	20030909	Probe card assembly and kit, and methods of making same	29/843	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078;	Eldridge; Benjamin Niles et al.

				257/E25.011; 257/E25.029; 29/842; 29/874; 324/756; 439/56; 439/591; 439/66	
US 6603324 B2	20030805	Special contact points for accessing internal circuitry of an integrated circuit	324/755	257/E23.079; 324/158.1; 324/756	Eldridge; Benjamin N. et al.
US 6599763 B1	20030729	Wafer randomization and alignment system integrated into a multiple chamber wafer processing system	438/14	414/935; 414/936; 438/17; 438/462	Reyes; Jose Carlos et al.
US 6597187 B2	20030722	Special contact points for accessing internal circuitry of an integrated circuit	324/754	257/E23.079; 324/158.1	Eldridge; Benjamin N. et al.
US 6596786 B2	20030722	Radiation-curable coating composition including oligomeric photoinitiator and/or oligomeric adhesion promoter	522/35	385/147; 428/378; 428/391; 428/394; 522/113; 522/116; 522/126; 522/127; 522/129; 522/130; 522/148; 522/150; 522/152; 522/41; 522/42; 522/43; 522/44; 522/45; 522/46; 522/63; 522/68; 522/90; 522/904; 522/96; 522/99;	Purvis; Michael B. et al.

				525/153; 525/158; 525/471	
US 6579914 B1	20030617	Coating compositions for optical waveguides and optical waveguides coated therewith	522/92	428/378; 428/426; 428/441; 522/100; 522/101; 522/103; 522/111; 522/113; 522/122; 522/134; 522/143; 522/25; 522/28; 522/7; 522/90; 522/96	Gantt; Todd W. et al.
US 6551844 B1	20030422	Test assembly including a test die for testing a semiconductor product die	438/14	257/E23.021; 257/E23.068; 257/E23.078; 438/15; 438/17	Eldridge; Benjamin N. et al.
US 6547861 B2	20030415	Method and materials for purifying reactive gases using preconditioned ultra- low emission carbon material	96/108	502/416; 502/519	Funke; Hans H. et al.
US 6544838 B2	20030408	Method of deep trench formation with improved profile control and surface area	438/244	257/E21.218; 257/E21.232; 438/243; 438/386; 438/387	Ranade; Rajiv et al.
US 6538214 B2	20030325	Method for manufacturing raised electrical contact pattern of controlled geometry	174/267	257/E21.503; 257/E21.508; 257/E23.021; 257/E23.025; 257/E23.068; 29/842; 29/874; 29/884; 29/885; 29/896.9; 361/769;	Khandros; Igor Y.

				361/774; 361/776; 439/78; 439/81; 439/876; 439/886; 439/887	
US 6534856 B1	20030318	Sockets for "springed" semiconductor devices	257/698	257/773; 257/E23.004; 257/E23.078; 257/E23.172; 257/E23.181; 439/66; 439/68; 439/70; 439/71; 439/72; 439/73	Dozier, II; Thomas H. et al.
US 6526803 B1	20030304	Apparatus and method for generating moisture standards in gases	73/1.04		Fraenkel; Dan et al.
US 6525555 B1	20030225	Wafer-level burn-in and test	324/765	324/754; 324/760	Khandros; Igor Y. et al.
US 6524372 B1	20030225	Silica gel incorporating polyazacycloalkane structural units	95/138	210/687; 423/219; 423/239.1; 423/584; 502/405; 502/407; 516/101; 540/474	Corriu; Robert et al.
US 6520778 B1	20030218	Microelectronic contact structures, and methods of making same	439/66	257/E23.021; 257/E23.068; 257/E23.078; 324/762	Eldridge; Benjamin N. et al.
US 6509751 B1	20030121	Planarizer for a semiconductor contactor	324/754		Mathieu; Gaetan L. et al.
US 6491968 B1	20021210	Methods for making spring interconnect structures	29/842	156/344; 29/874; 29/885; 427/97.3; 427/97.4	Mathieu; Gaetan L. et al.
US 6489376 B1	20021203	Formulation of UV- curable coatings for optical fiber for a fast	522/96	522/120; 522/121; 522/150;	Khudyakov; Igor V. et al.

		cure		522/151; 522/152; 522/181; 522/182; 522/40; 522/77; 522/90; 522/97	
US 6489249 B1	20021203	Elimination/reduction of black silicon in DT etch	438/729	156/345.3; 156/915; 216/67; 257/E21.218; 438/710	Mathad; Gangadhara S. et al.
US 6483328 B1	20021119	Probe card for probing wafers with raised contact elements	324/754	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 324/761	Eldridge; Benjamin N. et al.
US 6482013 B2	20021119	Microelectronic spring contact element and electronic component having a plurality of spring contact elements	439/66	324/762	Eldridge; Benjamin N. et al.
US 6476333 B1	20021105	Raised contact structures (solder columns)	174/267	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.067; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029	Khandros; Igor Y. et al.
US 6475822 B2	20021105	Method of making microelectronic contact	438/52	438/117; 438/14;	Eldridge; Benjamin N.

		structures		438/15	et al.
US 6470128 B1	20021022	UV-curable coating composition for optical fiber for a fast cure and with improved adhesion to glass	385/128	385/123; 385/141; 428/378; 522/96	Khudyakov; Igor et al.
US 6465893 B1	20021015	Stacked chip assembly	257/777	257/686; 257/E21.511; 257/E21.606; 257/E21.705; 257/E23.004; 257/E23.019; 257/E23.061; 257/E23.065; 257/E23.066; 257/E23.067; 257/E23.124; 257/E23.13; 257/E25.029	Khandros; Igor Y. et al.
US 6461411 B1	20021008	Method and materials for purifying hydride gases, inert gases, and non-reactive gases	95/116	502/415; 95/900	Watanabe; Tadaharu et al.
US 6456099 B1	20020924	Special contact points for accessing internal circuitry of an integrated circuit	324/754	257/E23.079; 324/158.1	Eldridge; Benjamin N. et al.
US 6447745 B1	20020910	Catalytic oxidation process	423/648.1	252/373; 423/418.2; 423/437.1; 423/651	Feeley; Jennifer Schaefer et al.
US 6442831 B1	20020903	Method for shaping spring elements	29/843	228/188; 228/199; 228/246; 29/841	Khandros; Igor Y. et al.
US 6441315 B1	20020827	Contact structures with blades having a wiping motion	174/260	174/267; 438/117	Eldridge; Benjamin N. et al.
US 6438111 B1	20020820	Dynamically scaleable conference system	370/260		Catanzaro; Anthony James et al.
US 6433419 B1	20020813	Face-up semiconductor chip assemblies	257/698	257/700; 257/702; 257/731; 257/737; 257/747;	Khandros; Igor Y. et al.

				257/748; 257/758; 257/759; 257/778; 257/779; 257/782; 257/783; 257/786; 257/788; 257/E21.511; 257/E21.606; 257/E21.705; 257/E23.004; 257/E23.019; 257/E23.061; 257/E23.065; 257/E23.066; 257/E23.067; 257/E23.07; 257/E23.124; 257/E23.13; 257/E25.029	
US 6429783 B1	20020806	Apparatus for indicating operational status of semiconductor fabrication equipment	340/815.4	340/468; 340/473; 340/679	Reyes; Jose Carlos et al.
US 6429029 B1	20020806	Concurrent design and subsequent partitioning of product and test die	438/14	257/E23.021; 257/E23.068; 257/E23.078; 438/10; 438/17	Eldridge; Benjamin N. et al.
US 6425946 B1	20020730	Method and apparatus for removing trace impurities from a gas using superactivated carbon material	96/108	502/416; 502/519	Funke; Hans H. et al.
US 6400139 B1	20020604	Methods and apparatus for electromagnetic position and orientation tracking with distortion compensation	324/207.17	324/207.12; 342/463	Khalfin; Igor et al.
US 6395070 B1	20020528	Methods for removal of impurity metals from gases using low metal zeolites	95/117	502/78; 502/79; 95/126; 95/132; 95/902	Bhadha; Paul M. et al.

US 6392306 B1	20020521	Semiconductor chip assembly with anisotropic conductive adhesive connections	257/783	257/784; 257/E21.511; 257/E21.606; 257/E21.705; 257/E23.004; 257/E23.019; 257/E23.061; 257/E23.065; 257/E23.066; 257/E23.067; 257/E23.124; 257/E23.13; 257/E25.029	Khandros; Igor Y. et al.
US 6377041 B1	20020423	Method and apparatus for determining electromagnetic field characteristics within a volume	324/244	324/207.12; 702/94	Jones, Jr.; Herbert R. et al.
US 6372527 B1	20020416	Methods of making semiconductor chip assemblies	438/15	257/E21.511; 257/E21.606; 257/E21.705; 257/E23.004; 257/E23.019; 257/E23.061; 257/E23.065; 257/E23.066; 257/E23.067; 257/E23.124; 257/E23.13; 257/E25.029; 438/113; 438/125	Khandros; Igor Y. et al.
US 6370634 B1	20020409	Data flow computer with two switches	712/10		Burtsev; Vsevolod Sergeevich et al.
US 6369564 B1	20020409	Electromagnetic position and orientation tracking system with distortion compensation employing wireless sensors	324/207.17	324/207.12; 702/150	Khalfin; Igor et al.
US 6359236 B1	20020319	Mounting component with leads having polymeric strips	174/261	174/250; 257/E23.065; 257/E23.066; 257/E23.07;	DiStefano; Thomas H. et al.

				257/E23.124; 361/760; 361/774; 439/74; 439/84	
US 6336269 B1	20020108	Method of fabricating an interconnection element	29/885	228/180.5; 228/199; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 29/825; 29/830; 29/840; 29/843	Eldridge; Benjamin N. et al.
US 6330164 B1	20011211	Interconnect assemblies and methods including ancillary electronic component connected in immediate proximity of semiconductor device	361/760	257/724; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 361/734; 361/738; 361/767; 361/769; 361/770; 361/773; 361/774; 361/783; 361/787;	Khandros; Igor Y. et al.

				361/804; 439/69	
US 6325307 B1	20011204	Method for producing powder from polymeric material and device for its realization	241/23	241/260.1; 241/65	Nikolskii; Vadim Gennadjevich et al.
US 6316105 B1	20011113	Radiation curable coating composition with hydrophobic properties for optical fibers and optical fibers coated thereby	428/378	385/145; 522/117; 522/137; 522/172; 522/173; 522/182; 522/85; 522/91; 522/96	Khudyakov; Igor V. et al.
US 6307161 B1	20011023	Partially-overcoated elongate contact structures	174/260	174/267; 257/E21.508; 257/E23.068; 361/774	Grube; Gary W. et al.
US 6292307 B1	20010918	Automatically focusing an optical instrument having a lens with only two focus positions	359/698		Wu; Jing et al.
US 6284666 B1	20010904	Method of reducing RIE lag for deep trench silicon etching	438/713	257/E21.218; 257/E21.232; 438/714; 438/733	Naeem; Munir D. et al.
US 6279227 B1	20010828	Method of forming a resilient contact structure	29/885	257/738; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.067; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 29/840; 29/843; 439/66; 439/83; 439/876	Khandros; Igor Y. et al.

US 6274823 B1	20010814	Interconnection substrates with resilient contact structures on both sides	174/261	174/260; 174/267; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.067; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 361/773; 361/774; 361/776; 439/81; 439/91	Khandros; Igor Y. et al.
US 6272744 B1	20010814	Semiconductor connection components and methods with releasable lead support	29/832	257/E23.065; 257/E23.066; 257/E23.07; 257/E23.124; 29/827; 29/840; 29/844	DiStefano; Thomas H. et al.
US 6268015 B1	20010731	Method of making and using lithographic contact springs	430/313	427/272; 427/282; 427/307; 427/97.4; 427/98.5; 427/99.3; 430/314; 430/315; 430/319; 430/320	Mathieu; Gaetan L. et al.
US 6255126 B1	20010703	Lithographic contact elements	438/15	438/14; 438/16; 438/597; 438/977	Mathieu; Gaetan L. et al.
US 6252301 B1	20010626	Compliant semiconductor chip assemblies and methods of making same	257/690	257/700; 257/773; 257/E21.514; 257/E23.065	Gilleo; Kenneth B. et al.
US 6252175	20010626	Electronic assembly	174/250	174/257;	Khandros;

B1		comprising a substrate and a plurality of springable interconnection elements secured to terminals of the substrate		257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.025; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 361/769; 361/771; 361/774; 361/776; 439/876; 439/886; 439/887	Igor Y.
US 6250756 B1	20010626	Biased eyeglass frames	351/126	351/124	Jannard; James H. et al.
US 6246247 B1	20010612	Probe card assembly and kit, and methods of using same	324/761	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 324/754	Eldridge; Benjamin N. et al.
US 6243800 B1	20010605	Computer	712/25	712/18; 712/201; 712/202; 712/32	Burtsev; Vsevolod Sergeevich et al.
US 6242803 B1	20010605	Semiconductor devices with integral contact structures	257/750	257/762; 257/763; 257/764; 257/765; 257/766;	Khandros; Igor Y. et al.

				257/784; 257/786; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.067; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 361/776	
US 6232149 B1	20010515	Sockets for "springed" semiconductor devices	438/117	257/E23.004; 257/E23.078; 257/E23.172; 257/E23.181; 29/739; 29/740; 29/741; 29/832; 361/769; 439/359; 439/81; 439/816	Dozier, II; Thomas H. et al.
US 6232125 B1	20010515	Method and apparatus for differentiating and enumerating leukocytes	436/63	356/317; 356/318; 356/337; 356/340; 356/39; 422/73; 435/2; 436/10; 436/150; 436/164; 436/8	Deka; Chiranjit et al.
US 6230734 B1	20010515	Flow-rate controller	137/220	137/501	Grebnev; Mikhail Jurievich et al.
US 6224690 B1	20010501	Flip-Chip interconnections using lead-free solders	148/400	257/738; 257/751; 257/753;	Andricacos; Panayotis Constantinou

				257/766; 257/E23.021	et al.
US 6215670 B1	20010410	Method for manufacturing raised electrical contact pattern of controlled geometry	361/774	257/696; 257/697; 257/750; 257/784; 257/E21.503; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 29/843; 361/769; 361/773; 361/776; 439/66; 439/876; 439/886	Khandros; Igor Y.
US 6215196 B1	20010410	Electronic component with terminals and spring contact elements extending from areas which are remote from the terminals	257/784	257/773; 257/E23.021; 257/E23.068	Eldridge; Benjamin N. et al.
US 6184587 B1	20010206	Resilient contact structures, electronic interconnection component, and method of mounting resilient contact structures to electronic components	257/784	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.067; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 361/776	Khandros; Igor Y. et al.
US 6184053 B1	20010206	Method of making microelectronic spring	438/52	438/117	Eldridge; Benjamin N.

		contact elements			et al.
US 6171698 B1	20010109	Radiation curable coating composition for optical fibers and optical fibers coated thereby	428/378	385/123; 522/148; 522/80; 522/84; 522/99; 524/858; 524/859; 528/26; 528/32; 528/38	Khudyakov; Igor V. et al.
US 6168974 B1	20010102	Process of mounting spring contacts to semiconductor devices	438/109	438/110; 438/113; 438/117; 438/652	Chang; Sung Chul et al.
US 6168271 B1	20010102	Decentered noncorrective lens for eyewear	351/41	351/178	Houston; Malcolm Neal et al.
US 6149368 A	20001121	Wafer disk pad having one or more wafer loading points to facilitate vacuum wand wafer loading and unloading	414/416.01	206/710; 414/936; 414/937; 414/941	Reyes, Jr.; J. Carlos et al.
US 6135451 A	20001024	Computer programming board game and method of play	273/236	273/242	Kholodov; Igor
US 6133627 A	20001017	Semiconductor chip package with center contacts	257/692	257/701; 257/E21.511; 257/E23.004; 257/E23.019; 257/E23.067; 257/E23.07; 257/E23.124; 257/E23.13	Khandros; Igor Y. et al.
US 6110823 A	20000829	Method of modifying the thickness of a plating on a member by creating a temperature gradient on the member, applications for employing such a method, and structures resulting from such a method	438/660	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078;	Eldridge; Benjamin N. et al.

				257/E25.011; 257/E25.029; 438/14; 438/597; 438/612	
US 6110258 A	20000829	Methods for removal of water from gases using superheated zeolites	95/117	502/78; 502/79; 95/126; 95/902	Fraenkel; Dan et al.
US 6106116 A	20000822	Biased eyeglass frames	351/41	351/159	Houston; Malcolm Neal et al.
US 6090261 A	20000718	Method and apparatus for controlling plating over a face of a substrate	427/99.5	205/125; 205/137; 205/915; 205/920; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 427/304; 427/425	Mathieu; Gaetan L.
US 6090237 A	20000718	Apparatus for restraining adhesive overflow in a multilayer substrate assembly during lamination	156/323	156/89.19; 29/848	Reynolds; Carl V. et al.
US D427414 S	20000704	Mountain-shaped chocolate piece	D1/127		Despland; Claude Andre et al.
US 6064213 A	20000516	Wafer-level burn-in and test	324/754	324/757; 324/760; 324/762	Khandros; Igor Y. et al.
US 6056399 A	20000502	Interchangeable nosepiece system	351/126	351/124	Jannard; James H. et al.
US 6054756	20000425	Connection components	257/668	257/670;	DiStefano;

A		with frangible leads and bus		257/676; 257/692; 257/735; 257/E23.055; 257/E23.065; 257/E23.066; 257/E23.07; 257/E23.124	Thomas H. et al.
US 6050829 A	20000418	Making discrete power connections to a space transformer of a probe card assembly	439/67	324/761	Eldridge; Benjamin N. et al.
US 6049976 A	20000418	Method of mounting free-standing resilient electrical contact structures to electronic components	29/843	228/180.5; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 267/158; 267/160; 267/182; 29/842; 29/874; 29/896.9; 439/81	Khandros; Igor Y.
US 6043895 A	20000328	Radiation probe with flexible sleeve	356/436	385/12	Masterson; Brian K. et al.
US 6043563 A	20000328	Electronic components with terminals and spring contact elements extending from areas which are remote from the terminals	257/784	257/773; 257/E21.09; 257/E23.021; 257/E23.068; 257/E23.078; 257/E23.142	Eldridge; Benjamin N. et al.
US 6042712 A	20000328	Apparatus for controlling plating over a face of a substrate	205/209	118/59; 118/666; 204/224R; 204/237; 204/241; 204/275.1;	Mathieu; Gaetan L.

				205/224; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 427/430.1; 427/434.3	
US 6033935 A	20000307	Sockets for "springed" semiconductor devices	438/117	257/E23.004; 257/E23.078; 257/E23.172; 257/E23.181; 438/455; 438/464; 438/667	Dozier, II; Thomas H. et al.
US 6032356 A	20000307	Wafer-level test and burn-in, and semiconductor process	29/843	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 29/842; 29/874; 324/756; 439/56; 439/591; 439/66	Eldridge; Benjamin N. et al.
US 6029344 A	20000229	Composite interconnection element for microelectronic components, and	29/874	216/14; 257/E21.503; 257/E21.508; 257/E21.509;	Khandros; Igor Y. et al.

		method of making same		257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 29/885; 29/896.9	
US 6023103 A	20000208	Chip-scale carrier for semiconductor devices including mounted spring contacts	257/781	257/784	Chang; Sung Chul et al.
US 6020220 A	20000201	Compliant semiconductor chip assemblies and methods of making same	438/119	257/E21.514; 257/E23.065; 438/118	Gilleo; Kenneth B. et al.
US 6010218 A	20000104	Decentered noncorrective lens for eyewear	351/159	351/41	Houston; Malcolm Neal et al.
US 6010217 A	20000104	Optically corrected shield for safety helmet	351/159	2/9; 351/41	Houston; Malcolm Neal et al.
US 5998864 A	19991207	Stacking semiconductor devices, particularly memory chips	257/723	257/668; 257/686; 257/691; 257/698; 257/724; 257/730; 257/731; 257/777; 257/778; 257/786; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068;	Khandros; Igor Y. et al.

				257/E23.078; 257/E25.011; 257/E25.013; 257/E25.029; 361/735	
US 5998228 A	19991207	Method of testing semiconductor	438/15	228/179.1; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 324/754; 324/762; 428/601; 428/620	Eldridge; Benjamin N. et al.
US 5994152 A	19991130	Fabricating interconnects and tips using sacrificial substrates	438/617	438/117; 438/15	Khandros; Igor Y. et al.
US 5983493 A	19991116	Method of temporarily, then permanently, connecting to a semiconductor device	29/855	228/179.1; 228/180.21; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 29/840; 29/843	Eldridge; Benjamin N. et al.
US 5977618 A	19991102	Semiconductor connection components	257/674	174/260; 174/261;	DiStefano; Thomas H. et

		and methods with releasable lead support		228/180.21; 257/666; 257/669; 257/680; 257/698; 257/E23.065; 257/E23.066; 257/E23.07; 257/E23.124; 29/827	al.
US 5974662 A	19991102	Method of planarizing tips of probe elements of a probe card assembly	29/842	174/261; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.025; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 29/844; 324/754; 324/761; 361/772; 361/774; 361/776; 361/789	Eldridge; Benjamin N. et al.
US 5969789 A	19991019	Decentered noncorrective lens for eyewear	351/159	351/41	Houston; Malcolm Neal et al.
US 5958598 A	19990928	Radiation curable hardcoat compositions possessing anti-fog properties	428/447	427/379; 427/384; 427/387; 428/411.1; 428/412; 523/213; 524/790	Khudyakov; Igor V. et al.
US 5950304 A	19990914	Methods of making semiconductor chip assemblies	29/831	257/E21.511; 257/E21.606; 257/E21.705; 257/E23.004;	Khandros; Igor Y. et al.

				257/E23.019; 257/E23.061; 257/E23.065; 257/E23.066; 257/E23.067; 257/E23.124; 257/E23.13; 257/E25.029; 29/832; 29/840	
US 5928705 A	19990727	Cooked extruded meat product comprising additive and method for making the same	426/646	426/105; 426/516; 426/517; 426/518; 426/641; 426/90; 426/92	Matthews; Bernard Trevor et al.
US 5926951 A	19990727	Method of stacking electronic components	29/843	174/261; 257/738; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.067; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 29/829; 29/840; 29/842; 361/772; 361/776; 439/66	Khandros; Igor Y. et al.
US 5923525 A	19990713	Capacitor with double electric layer	361/502	361/503; 361/512	Belyakov; Alexei Ivanovich et al.
US 5917707 A	19990629	Flexible contact structure with an electrically conductive shell	361/776	228/179.1; 228/180.1; 228/180.5; 257/692;	Khandros; Igor Y. et al.

				257/736; 257/748; 257/750; 257/779; 257/784; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.067; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 29/850; 29/854; 29/881; 361/774; 361/779; 427/117; 427/118; 439/83; 439/84; 439/85	
US 5915752 A	19990629	Method of making connections to a semiconductor chip assembly	29/827	174/52.4; 257/735; 257/E23.055; 257/E23.065; 257/E23.066; 257/E23.07; 257/E23.124	DiStefano; Thomas H. et al.
US 5912046 A	19990615	Method and apparatus for applying a layer of flowable coating material to a surface of an electronic component	427/126.2	118/500; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068;	Eldridge; Benjamin N. et al.

				257/E23.078; 257/E25.011; 257/E25.029; 427/240	
US 5900738 A	19990504	Contact structure device for interconnections, interposer, semiconductor assembly and package using the same and method	324/761	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.067; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029	Khandros; Igor Y. et al.
US 5897326 A	19990427	Method of exercising semiconductor devices	438/14	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 438/117	Eldridge; Benjamin N. et al.
US 5887415 A	19990330	Cooked, extruded meat product comprising additive	53/576	452/45; 53/122; 53/237	Matthews; Bernard Trevor et al.
US 5884398 A	19990323	Mounting spring elements on semiconductor devices	29/843	228/180.5; 228/199; 257/777; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024;	Eldridge; Benjamin N. et al.

				257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029	
US 5878486 A	19990309	Method of burning-in semiconductor devices	29/840	257/620; 257/665; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 29/843; 438/14; 438/18	Eldridge; Benjamin N. et al.
US 5869415 A	19990209	Process for activating layered silicates	502/81	502/80; 502/83	Ortiz; Jose Antonio et al.
US 5864946 A	19990202	Method of making contact tip structures	29/843	174/261; 228/188; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 29/424; 324/754; 324/761	Eldridge; Benjamin N. et al.
US 5861266 A	19990119	Treatment of diabetes mellitus and insulin receptor signal transduction	435/21	424/130.1; 435/184; 514/2; 514/866	Ullrich; Axel et al.

US 5852871 A	19981229	Method of making raised contacts on electronic components	29/843	228/180.5; 228/199; 228/4.5; 257/777; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 324/754	Khandros; Igor Y.
US 5852326 A	19981222	Face-up semiconductor chip assembly	257/692	257/690; 257/701; 257/E21.511; 257/E23.004; 257/E23.019; 257/E23.067; 257/E23.124; 257/E23.13	Khandros; Igor Y. et al.
US 5848467 A	19981215	Methods of making semiconductor chip assemblies	29/841	257/E21.511; 257/E21.705; 257/E23.004; 257/E23.019; 257/E23.067; 257/E23.124; 257/E23.13; 257/E25.013; 29/832; 29/840; 29/842; 438/113	Khandros; Igor Y. et al.
US 5847384 A	19981208	Method for determining irregularities in a wellbore wall using a gamma-gamma well logging instrument	250/269.3	250/266	Mathis; Gary L.
US 5832601 A	19981110	Method of making temporary connections between electronic components	29/843	257/620; 257/665; 257/E21.503; 257/E21.508;	Eldridge; Benjamin N. et al.

				257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 29/840; 438/14; 438/18	
US 5829128 A	19981103	Method of mounting resilient contact structures to semiconductor devices	29/855	228/180.21; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 29/840; 29/843; 977/712; 977/723 CIPG 20060101 A B23K B23K20/00 L I R US M 20060101 CICL B23K CIPS B23K20/00 20060101 CIPG 20060101 A B23K B23K20/00	Eldridge; Benjamin N. et al.

				L I R US M 20060101 CICL B23K CIPS B23K20/00 20060101 CIPG 20060101 A C23C C23C18/16 L I R US M 20060101 CICL C23C CIPS C23C18/16; 20060101 CIPG 20060101 A C23C C23C18/16 L I R US M 20060101 CICL C23C CIPS C23C18/16 20060101 CIPG 20060101 A C25D C25D5/00 L N R US M 20060101 CICL C25D CIPN C25D5/00 20060101 CIPG 20060101 A C25D C25D5/08 L N R US M 20060101 CICL C25D CIPN C25D5/08; 20060101	
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				CIPG 20060101 A C25D C25D5/22 L N R US M 20060101 CICL C25D CIPN C25D5/22 20060101 CIPG 20060101 A C25D C25D7/12 L I R US M 20060101 CICL C25D CIPS C25D7/12 20060101 CIPG 20060101 A C25D C25D7/12 L I R US M 20060101 CICL C25D CIPS C25D7/12; 20060101 CIPG 20060101 A C25D C25D21/00 L N R US M 20060101 CICL C25D CIPN C25D21/00 20060101 CIPG 20060101 A C25D C25D21/02 L N R US M 20060101	
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				G01R G01R1/073 L I R US M 20060101 CICL G01R CIPS G01R1/073 20060101 CIPG 20060101 A G01R G01R1/073 L I R US M 20060101 CICL G01R CIPS G01R1/073 20060101 CIPG 20060101 A G01R G01R31/28 L N R US M 20060101 CICL G01R CIPN; G01R31/28 20060101 CIPG 20060101 A G01R G01R31/28 L N R US M 20060101 CICL G01R CIPN G01R31/28 20060101 CIPG 20060101 A H01L H01L21/00 L I R US M 20060101 CICL H01L CIPS	
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US 5820014 A	19981013	Solder preforms	228/56.3	228/246	Dozier, II; Thomas H. et al.
US 5806181 A	19980915	Contact carriers (tiles) for populating larger substrates with spring contacts	29/874	29/840; 324/756; 438/15; 439/54; 439/591; 439/66	Khandros; Igor Y. et al.
US 5805261 A	19980908	Biased eyeglass frames	351/126	351/124	Houston; Malcolm Neal et al.
US 5787581 A	19980804	Methods of making semiconductor connection components with releasable load support	29/884	174/267; 257/E23.065; 257/E23.066; 257/E23.07; 257/E23.124; 29/827; 29/882; 361/760	DiStefano; Thomas H. et al.
US 5773780 A	19980630	Method of severing bond wires and forming balls at their ends	219/56.22	219/69.1	Eldridge; Benjamin N. et al.
US 5772451 A	19980630	Sockets for electronic components and methods of connecting to electronic components	439/70	257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029;	Dozier, II; Thomas H. et al.

				439/66	
US 5759437 A	19980602	Etching of Ti-W for C4 rework	252/79.1	252/79.2; 257/E21.309; 438/754	Datta; Madhav et al.
US 5739181 A	19980414	Radiation curable hardcoat compositions possessing anti-fog properties	523/213	523/425; 524/265; 524/806; 524/837; 524/860; 526/307.5; 526/318.2; 526/321	Khudyakov; Igor V. et al.
US 5689323 A	19971118	Decentered noncorrective lens for eyewear	351/41	351/178	Houston; Malcolm Neal et al.
US 5685885 A	19971111	Wafer-scale techniques for fabrication of semiconductor chip assemblies	29/841	257/E21.511; 257/E21.606; 257/E21.705; 257/E23.004; 257/E23.019; 257/E23.065; 257/E23.067; 257/E23.124; 257/E23.13; 29/840; 29/842; 29/855	Khandros; Igor Y. et al.
US 5682061 A	19971028	Component for connecting a semiconductor chip to a substrate	257/666	257/669; 257/700; 257/E21.511; 257/E21.606; 257/E21.705; 257/E23.004; 257/E23.019; 257/E23.061; 257/E23.065; 257/E23.066; 257/E23.067; 257/E23.124; 257/E23.13; 361/769; 361/772; 361/776	Khandros; Igor Y. et al.
US 5679977 A	19971021	Semiconductor chip assemblies, methods of making same and	257/692	257/690; 257/701; 257/E21.511;	Khandros; Igor Y. et al.

		components for same		257/E21.606; 257/E21.705; 257/E23.004; 257/E23.019; 257/E23.061; 257/E23.065; 257/E23.066; 257/E23.067; 257/E23.124; 257/E23.13; 257/E25.029	
US 5659169 A	19970819	Formation density sensor having detector array and method of calculating bulk density and correction	250/269.3	250/265	Mickael; Medhat W. et al.
US 5648832 A	19970715	Decentered noncorrective lens for eyewear	351/159	351/41	Houston; Malcolm Neal et al.
US 5640761 A	19970624	Method of making multi-layer circuit	29/830	174/262; 257/E23.172; 29/846; 29/852; 427/97.2	DiStefano; Thomas H. et al.
US 5639683 A	19970617	Structure and method for intergrating microwave components on a substrate	438/107	257/E25.012; 257/E27.009; 438/108	Reyes; Adolfo Canuto
US 5601740 A	19970211	Method and apparatus for wirebonding, for severing bond wires, and for forming balls on the ends of bond wires	219/130.4	219/56.21; 219/56.22; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.519; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029	Eldridge; Benjamin N. et al.
US 5583321 A	19961210	Multi-layer circuit construction methods and structures with	174/264	174/250; 174/262; 257/E23.173	DiStefano; Thomas H. et al.

		customization features and components for use therein			
US 5570504 A	19961105	Multi-Layer circuit construction method and structure	29/830	257/E23.173; 29/846; 29/852; 427/97.2	DiStefano; Thomas H. et al.
US 5558928 A	19960924	Multi-layer circuit structures, methods of making same and components for use therein	428/209	174/258; 174/261; 174/262; 257/675; 257/E23.173; 29/830; 29/847; 29/852; 361/779; 361/795; 428/76	DiStefano; Thomas H. et al.
US 5536909 A	19960716	Semiconductor connection components and methods with releasable lead support	174/261	174/250; 174/260; 257/E23.065; 257/E23.066; 257/E23.07; 257/E23.124; 361/767	DiStefano; Thomas H. et al.
US 5530243 A	19960625	Formation density well logging tool with detector array for compensation of wellbore roughness and tool tilt	250/269.3	250/256; 250/264; 250/266; 250/269.1	Mathis; Gary L.
US 5525545 A	19960611	Semiconductor chip assemblies and components with pressure contact	438/15	257/E23.078; 29/593; 29/832; 438/125	Grube; Gary et al.
US 5489749 A	19960206	Semiconductor connection components and method with releasable lead support	174/261	174/260; 174/262; 257/E23.065; 257/E23.066; 257/E23.07; 257/E23.124; 29/832; 29/835; 361/760; 361/774; 361/783;	DiStefano; Thomas H. et al.

				439/78; 439/84	
US 5476211 A	19951219	Method of manufacturing electrical contacts, using a sacrificial member	228/180.5	228/199; 257/E21.503; 257/E21.508; 257/E21.509; 257/E21.511; 257/E21.512; 257/E21.525; 257/E23.021; 257/E23.024; 257/E23.068; 257/E23.078; 257/E25.011; 257/E25.029; 29/840; 29/843; 427/117	Khandros; Igor Y.
US 5448908 A	19950912	Device for the measurement of viscoelasticity of products, and particularly those with low viscosity	73/54.35		El Bounia; Nour-Eddine et al.
US 5445253 A	19950829	Shift control mechanism for a multi-speed countershaft transmission	74/339	192/53.1; 74/411.5	Reyes; Carlos C.
US 5414298 A	19950509	Semiconductor chip assemblies and components with pressure contact	257/690	257/692; 257/701; 257/E23.078	Grube; Gary et al.
US 5398863 A	19950321	Shaped lead structure and method	228/106	228/180.21	Grube; Gary W. et al.
US 5391510 A	19950221	Formation of self-aligned metal gate FETs using a benignant removable gate material during high temperature steps	438/301	257/E21.202; 257/E21.205; 257/E21.427; 257/E21.444; 257/E29.127; 257/E29.148; 438/305; 438/945	Hsu; Louis L. et al.
US 5390844 A	19950221	Semiconductor inner lead bonding tool	228/180.21	228/212; 228/49.5; 257/E21.519	Distefano; Thomas H. et al.
US 5378599	19950103	High bromide chloride	430/569	430/567	Maskasky;

A		containing silver iodohalide emulsions exhibiting an increased proportion of iodide			Joe E. et al.
US 5367764 A	19941129	Method of making a multi-layer circuit assembly	29/830	174/260; 174/262; 216/20; 257/E23.173; 29/852; 439/69	DiStefano; Thomas H. et al.
US 5347159 A	19940913	Semiconductor chip assemblies with face-up mounting and rear-surface connection to substrate	257/692	257/696; 257/E21.511; 257/E21.606; 257/E21.705; 257/E23.004; 257/E23.019; 257/E23.061; 257/E23.065; 257/E23.066; 257/E23.067; 257/E23.124; 257/E23.13	Khandros; Igor Y. et al.
US 5346861 A	19940913	Semiconductor chip assemblies and methods of making same	438/15	257/E21.511; 257/E21.606; 257/E21.705; 257/E23.004; 257/E23.019; 257/E23.061; 257/E23.065; 257/E23.066; 257/E23.067; 257/E23.124; 257/E23.13; 29/832; 438/113; 438/125	Khandros; Igor Y. et al.
US 5288603 A	19940222	High chloride silver iodohalide emulsions containing an increased proportion of iodide	430/567	430/569	Maskasky; Joe E. et al.
US 5282312 A	19940201	Multi-layer circuit construction methods with customization features	29/830	257/E23.173; 29/846; 29/852; 427/97.2; 430/315	DiStefano; Thomas H. et al.
US 5269491	19931214	High vacuum valve	251/195	251/169	Reynolds;

A					Calvin E.
US 5258330 A	19931102	Semiconductor chip assemblies with fan-in leads	29/593	257/E21.511; 257/E21.606; 257/E21.705; 257/E23.004; 257/E23.019; 257/E23.061; 257/E23.065; 257/E23.066; 257/E23.067; 257/E23.124; 257/E23.13; 29/827; 29/832; 438/125	Khandros; Igor Y. et al.
US 5258264 A	19931102	Process of forming a dual overhang collimated lift-off stencil with subsequent metal deposition	430/315	204/192.36; 216/40; 216/67; 216/79; 216/80; 257/E21.252; 257/E21.587; 427/534; 427/97.5; 430/313; 430/317; 430/324; 438/128; 438/598	Mathad; Gangadhara S. et al.
US 5253710 A	19931019	Method and apparatus to cut and remove casing	166/298	166/216; 166/301; 166/55.6	Carter; Thurman B. et al.
US 5238804 A	19930824	High bromide chloride containing silver iodohalide emulsions exhibiting an increased proportion of iodide	430/567	430/569	Maskasky; Joe E. et al.
US 5198189 A	19930330	Liquid metal matrix thermal paste	420/555	252/387; 257/E23.112	Booth; Richard B. et al.
US 5192618 A	19930309	Corrosion protection by FeMn by ion implantation	428/457	148/101; 148/222; 148/239; 204/157.4; 204/157.44; 204/157.46;	Frankel; Gerald S. et al.

				204/157.47; 204/157.5; 257/E43.006; 360/110; 360/327.32; 427/130; 428/469; 428/611; 428/632; 428/677; 428/681; 428/834; 428/920; 428/928	
US 5183072 A	19930202	Automatic switchover valve	137/113	137/505.14	Pengler; Rudolf
US 5173621 A	19921222	Transceiver with isolated power rails for ground bounce reduction	326/78	257/E23.043; 257/E23.079; 326/17; 326/33; 326/34	Fraser; Dana et al.
US 5173256 A	19921222	Liquid metal matrix thermal paste	420/590	257/E23.112	Booth; Richard B. et al.
US 5148266 A	19920915	Semiconductor chip assemblies having interposer and flexible lead	257/773	257/668; 257/669; 257/E21.511; 257/E21.606; 257/E21.705; 257/E23.004; 257/E23.019; 257/E23.061; 257/E23.065; 257/E23.066; 257/E23.067; 257/E23.124; 257/E23.13	Khandros; Igor Y. et al.
US 5148265 A	19920915	Semiconductor chip assemblies with fan-in leads	257/773	257/668; 257/669; 257/E21.511; 257/E21.606; 257/E21.705; 257/E23.004; 257/E23.019; 257/E23.061; 257/E23.065;	Khandros; Igor Y. et al.

				257/E23.066; 257/E23.067; 257/E23.124; 257/E23.13	
US 5134038 A	19920728	Thin film magnetic recording medium with controlled grain morphology and topology	428/611	360/134; 360/135; 360/136; 428/336; 428/612; 428/614; 428/621; 428/642; 428/660; 428/661; 428/831.2; 428/900; 428/928; 428/939	Baseman; Robert J. et al.
US 5086558 A	19920211	Direct attachment of semiconductor chips to a substrate with a substrate with a thermoplastic interposer	29/832	257/E21.503; 257/E21.511; 257/E21.519; 257/E23.067; 29/840; 29/841	Grube; Gary W. et al.
US 5065224 A	19911112	Low noise integrated circuit and leadframe	257/666	257/676; 257/692; 257/E23.043; 257/E23.079	Fraser; Dana et al.
US 5062896 A	19911105	Solder/polymer composite paste and method	106/287.19	148/24; 252/512; 252/514	Huang; Wu- Song et al.
US 5024896 A	19910618	Collimated metal deposition	428/473.5	174/254; 257/E21.252; 257/E21.587; 428/601; 428/620; 428/901; 430/273.1; 430/312	Mathad; Gangadhara S. et al.
US 4841084 A	19890620	New hexacoordinate silicon complexes, the process for their preparation and their application	556/464	556/406; 556/430; 556/449; 556/466; 556/478; 556/487; 556/489	Corriu; Robert J. et al.

US 4835316 A	19890530	New organomagnesium complexes in solid form, process for their preparation, and their use	564/505	260/665G; 564/346	Corriu; Robert et al.
US 4741799 A	19880503	Anisotropic silicon etching in fluorinated plasma	438/695	204/192.37; 252/79.1; 257/E21.218; 438/700	Chen; Lee et al.
US 4730263 A	19880308	Method and device for measuring gamma radiation	702/88	324/256; 324/335; 378/70	Mathis; Gary L.
US 4717290 A	19880105	Milling tool	407/34	175/377; 299/112R; 407/59	Reynolds; Carl D. et al.
US 4671849 A	19870609	Method for control of etch profile	438/713	204/192.34; 257/E21.252; 438/714; 438/723; 438/743	Chen; Lee et al.
US 4665209 A	19870512	Process for the preparation of hydrogenosilanes or halogenosilanes	556/474	556/477	Corriu; Robert J. et al.
US D287343 S	19861223	Flowmeter	D10/96	D10/101	Waters; Craig
US 4625627 A	19861202	Ventilated cabinet for containing gas supply vessels	454/237	454/370; 454/49	Livanos; Vassilios J. et al.
US 4618009 A	19861021	Reaming tool	175/267	175/269	Carter; Thurman B. et al.
US 4617730 A	19861021	Method of fabricating a chip interposer	29/843	174/258; 174/259; 174/267; 257/697; 257/774; 257/E23.067; 257/E23.172; 29/853; 427/97.2	Geldermans; Pieter et al.
US 4617413 A	19861014	Pentacoordinate silicon complexes, the process for their preparation and their application to the preparation of	556/464	556/406; 556/463; 556/466; 556/478; 556/487;	Corriu; Robert J. et al.

		organosilanes		556/489	
US 4602981 A	19860729	Monitoring technique for plasma etching	438/17	204/192.33; 204/298.32; 438/710	Chen; Lee et al.
US D283805 S	19860513	Flowmeter	D10/96	D10/101	Waters; Craig
US D283804 S	19860513	Flowmeter	D10/96		Waters; Craig
US 4588680 A	19860513	Assay for viruses	435/5	435/188; 435/7.92; 435/961; 435/962; 436/531	Bucher; Doris J. et al.
US 4582217 A	19860415	Sealable fluid containment assembly	220/582	220/288; 220/327	Proctor; James A. et al.
US 4562339 A	19851231	Inserted product newspaper sensor	235/98R	235/98B; 377/8	Sjogren; Christer A. et al.
US 4536232 A	19850820	Erosion and corrosion resistant cast iron alloy containing chromium, nickel and molybdenum	148/542	148/324; 148/335; 148/616	Khandros; Igor Y. et al.
US 4534816 A	19850813	Single wafer plasma etch reactor	156/345.37	156/345.53; 204/298.33; 438/715	Chen; Lee et al.
US 4511430 A	19850416	Control of etch rate ratio of SiO ₂ /photoresist for quartz planarization etch back process	438/723	204/192.32; 252/79.1; 257/E21.245; 257/E21.252; 257/E21.256; 438/697; 438/725	Chen; Lee et al.
US 4510363 A	19850409	Kiln for hot-pressing compacts in a continuous manner	219/656	100/92; 219/388; 219/659; 425/407; 432/143; 432/163	Reynolds, Jr.; Carl D.
US 4490211 A	19841225	Laser induced chemical etching of metals with excimer lasers	216/62	216/65; 216/78; 219/121.69; 438/705; 438/708	Chen; Lee et al.
US 4490210 A	19841225	Laser induced dry chemical etching of	216/65	216/75; 216/78;	Chen; Lee et al.

		metals		219/121.69; 438/708	
US 4478677 A	19841023	Laser induced dry etching of vias in glass with non-contact masking	216/65	156/345.5; 216/54; 216/79; 216/80; 219/121.69; 219/121.71; 219/121.85; 438/708	Chen; Lee et al.
US 4431477 A	19840214	Plasma etching with nitrous oxide and fluoro compound gas mixture	438/719	204/192.32; 252/79.1; 257/E21.252; 257/E21.312; 438/724	Zajac; John
US 4424853 A	19840110	Foundry practices	164/57.1	164/66.1	Khandros; Igor Y. et al.
US 4380752 A	19830419	Automatic transmission selector lever lock	340/457	340/456; 70/254	Reynolds; Carlton J.
US 4377196 A	19830322	Method of centrifugally casting a metal tube	164/66.1	164/114; 164/95; 164/96	Khandros; Igor Y.
US 4357394 A	19821102	Centrifugal casting	428/595	138/143; 428/610; 428/652; 428/653	Khandros; Igor Y.
US 4303980 A	19811201	Electromagnetic flowmeter system having automatically adjusted response characteristics	702/49	73/861.17	Yard; John S.
US 4215088 A	19800729	Method for fabricating boron carbide articles	264/332	156/304.1; 156/89.11	Ardary; Zane L. et al.
US 4152482 A	19790501	Anisotropic fibrous thermal insulator of relatively thick cross section and method for making same	442/391	156/245; 156/285; 264/29.2; 264/29.5; 264/29.7; 423/294; 423/323; 423/445R; 423/447.2; 428/402; 428/408; 428/910; 428/920	Reynolds; Carl D. et al.

US 4042976 A	19770823	Protective collar	2/135	2/203	Reynolds; Jay Carter
US 3997789 A	19761214	Neutron-irradiation dose monitor comprising thermocouples	250/390.03		Mathieu; Francois Gaspard
US 3952493 A	19760427	Apparatus for ringless spinning of fibers	57/414	57/415	Khomyakov; Igor Stepanovich et al.
US 3922367 A	19751125	Preparation for imparting smoke to meat products	426/536	426/534; 426/650	Gorbatov; Vasily Matveevich et al.
US 3889318 A	19750617	Device for feeding lap of fibres to carding member of ringless spinning apparatus	19/105	19/128	Leinek; Albert Arturovich et al.
US 3875731 A	19750408	Apparatus for ringless spinning of fibre	57/417	57/414	Khomyakov; Igor Stepanovich et al.
US 3793204 A	19740219	THERMAL INSULATION	252/62	264/29.1; 428/338; 428/364; 428/367; 428/401; 428/408	Ardary; Zane L. et al.
US 3743458 A	19730703	APPARATUS FOR INJECTION MOLDING ARTICLES CARRYING DECORATIONS PUNCHED FROM A BAND	425/122	264/275; 425/112; 425/129.1	Hallauer; Siegfried et al.
US 3674270 A	19720704	BASKET GAME UTILIZING CONVEXLY SHAPED PADDLES AND AN IRREGULARLY SHAPED BALL	273/400	473/595	Benjamin; Thaer L. et al.
US 3274049 A	19660920	Process for pulping bagasse with ammonium hydroxide and oxygen [TEXT AVAILABLE IN	162/65	162/90; 162/96; 71/23; 71/25	MATHEW GASCHKE MARCEL et al.

		USOCR DATABASE]			
US 3230952 A	19660125	Orthopedic apparatus having an improved joint construction [TEXT AVAILABLE IN USOCR DATABASE]	602/16	403/113; 602/23	REYES TERRON CANDIDO
US 3187347 A	19650608	Joint arrangement with multi-positional locking means for a prosthetic surgical appliance [TEXT AVAILABLE IN USOCR DATABASE]	623/43	33/341; 403/102; 403/410	REYES TERRON CANDIDO
US 3120170 A	19640204	Coffee making device [TEXT AVAILABLE IN USOCR DATABASE]	99/287	210/352; 417/478; 417/480; 99/302FB	MATHEW GARTE
US 3073523 A	19630115	Game scoring and subject-designating device [TEXT AVAILABLE IN USOCR DATABASE]	235/114	116/223; 235/1B; 273/148R	MATHER GARLAND
US 2795889 A	19570618	Live fish bag for fishing by boat or by wading [TEXT AVAILABLE IN USOCR DATABASE]	43/55	224/406; 224/667; 224/677; 224/920; 43/11	MATHER GARLAND
US 2795888 A	19570618	Receptacle for live fish [TEXT AVAILABLE IN USOCR DATABASE]	43/55	43/11	MATHER GARLAND
US 2795804 A	19570618	Attachable oarlock-mounting [TEXT AVAILABLE IN USOCR DATABASE]	440/109		MATHER GARLAND
US 2696400 A	19541207	Carton carrier [TEXT AVAILABLE IN USOCR DATABASE]	294/87.2	206/431; 211/74; 229/117.14; 229/120.18; 229/194; 248/312	REYNA CARL A et al.
US 2694596 A	19541116	Carton carrier [TEXT AVAILABLE IN USOCR DATABASE]	294/87.2	206/431; 211/74; 229/117.14; 229/120.18;	HAROLD GREENLAW et al.

				229/194; 24/16R; 248/312	
US 2693385 A	19541102	Carton carrier and cover [TEXT AVAILABLE IN USOCR DATABASE]	206/431	211/74; 229/117.22; 248/312; 294/87.2	CAVALLI LOUIS W et al.
US 2677346 A	19540504	Television receiver tuning indicator [TEXT AVAILABLE IN USOCR DATABASE]	116/262	116/282; 116/DIG.31; 280/124.152	MYERS WILLIAM H et al.
US 2635238 A	19530421	Apparatus for clamping umbilical cords and the like [TEXT AVAILABLE IN USOCR DATABASE]	606/142	29/268; 40/304; 606/120; 81/418; 81/426	MATHER GARLAND
US 2626608 A	19530127	Clamp for umbilical cords and the like [TEXT AVAILABLE IN USOCR DATABASE]	606/120		MATHER GARLAND
US 2598901 A	19520603	Clamp for constricting flexible tubular elements and the like [TEXT AVAILABLE IN USOCR DATABASE]	606/120	24/30.5W; 24/508; 24/703.1; 251/9; 72/409.19; D11/87	MATHER GARLAND
US 2598249 A	19520527	Rotary snowplow [TEXT AVAILABLE IN USOCR DATABASE]	37/256	37/232	MATHER GARLAND
US 2536166 A	19510102	Rotary snowplow for driveways, sidewalks, etc. [TEXT AVAILABLE IN USOCR DATABASE]	37/245	180/9; 37/256; 37/260; 37/270	MATHER GARLAND
US 2453037 A	19481102	Nail puller [TEXT AVAILABLE IN USOCR DATABASE]	254/21		REYNOLDS CARL W
US 2341862 A	19440215	Traffic signal [TEXT AVAILABLE IN USOCR DATABASE]	315/90	362/242	MATHER GARLAND
US 2296518 A	19420922	Driving connection with focusing mechanism [TEXT AVAILABLE IN USOCR	74/385	464/117	RUSSELL GREER EDWARD et al.

		DATABASE]			
US 2241252 A	19410506	Snowplow with power discharge [TEXT AVAILABLE IN USOCR DATABASE]	37/236	37/254; 37/270; 37/279	MATHER GARLAND et al.
US 2199723 A	19400507	Snowplow structure [TEXT AVAILABLE IN USOCR DATABASE]	37/247		MATHER GARLAND et al.
US 2147799 A	19390221	Gutter mounting device [TEXT AVAILABLE IN USOCR DATABASE]	248/48.2		REYNOLDS CARL W
US 1936506 A	19331121	Temperature control and ventilating system for vehicles [TEXT AVAILABLE IN USOCR DATABASE]	62/282	454/107; 62/241; 62/317; 62/337; 62/416	MATHER GARLAND
US 1935485 A	19331114	Corner cushion [TEXT AVAILABLE IN USOCR DATABASE]	5/633	297/219.1; 5/630	REYNOLDS CARRIE M
US 1810789 A	19310616	Liquid purification system [TEXT AVAILABLE IN USOCR DATABASE]	210/93	210/167; 210/181; 210/258; 210/95; 68/18F	REYNOLDS CARL C
US 1640986 A	19270830	Ventilating apparatus [TEXT AVAILABLE IN USOCR DATABASE]	454/138		MATHER GARLAND
US 1621531 A	19270322	Ventilator [TEXT AVAILABLE IN USOCR DATABASE]	454/116		MATHER GARLAND MAMIE